

DALLAS

SEMICONDUCTOR

DS1235Y/AB

256K Nonvolatile SRAM

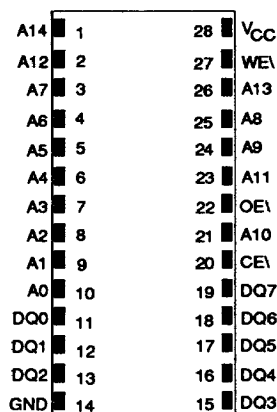
FEATURES

- Data retention in the absence of V_{CC}
- Data is automatically protected during power loss
- Directly replaces 32K x 8 volatile static RAMs or EEPROMs
- Unlimited write cycles
- Low-power CMOS
- Over 5 years of data retention
- Standard 28-pin JEDEC pinout
- Available in 100, 120, 150, and 200 ns read access times
- Read cycle time equals write cycle time
- Lithium energy source is electrically disconnected to retain freshness until power is applied for the first time
- Full $\pm 10\%$ operating range (DS1235Y)
- Optional $\pm 5\%$ operation range (DS1235AB)

DESCRIPTION

The DS1235Y/AB 256K Nonvolatile SRAM is a 262, 144-bit, fully static SRAM organized as 32,768 words by 8 bits. The nonvolatile memory has a self-contained lithium energy source and control circuitry that constantly monitors V_{CC} for an out-of-tolerance condition. When such a condition occurs, the lithium energy source is automatically switched on and write protection is unconditionally enabled to prevent garbled data.

PIN DESCRIPTION



28-PIN ENCAPSULATED PACKAGE
(720 Mil Extended)

PIN NAMES (\ Denotes Condition Low)

A0 - A14	- Address Inputs
CE\	- Chip Enable
GND	- Ground
DQ0-DQ7	- Data In/Data Out
V_{CC}	- Power (+5V)
WE\	- Write Enable
OE\	- Output Enable

The nonvolatile SRAM can be used in place of existing 32K x 8 SRAMs directly conforming to the popular byte-wide 28256 EEPROM, allowing direct substitution while enhancing performance. There is no limit on the number of write cycles that can be executed and no additional support circuitry is required for microprocessor interface.

READ MODE

The DS1235Y/AB executes a read cycle whenever \overline{WE} (Write Enable) is inactive (high) and \overline{CE} (Chip Enable) is active (low). The unique address specified by the 15 address inputs (A_0 – A_{14}) defines which of the 32,768 bytes of data is to be accessed. Valid data will be available to the eight data output drivers within t_{ACC} (Access Time) after the last address input signal is stable, providing that \overline{CE} and \overline{OE} (Output Enable) access times are also satisfied. If \overline{OE} and \overline{CE} access times are not satisfied, then data access must be measured from the later occurring signal (\overline{CE} or \overline{OE}) and the limiting parameter is either t_{CO} for \overline{CE} or t_{OE} for \overline{OE} , rather than address access.

WRITE MODE

The DS1235Y/AB is in the write mode whenever the \overline{WE} and \overline{CE} signals are in the active (low) state after address inputs are stable. The latter occurring falling edge of \overline{CE} or \overline{WE} will determine the start of the write cycle. The write cycle is terminated by the earlier rising edge of \overline{CE} or \overline{WE} . All address inputs must be kept valid throughout the write cycle. \overline{WE} must return to the high state for a minimum recovery time (t_{WR}) before another cycle can be initiated. The \overline{OE} control signal should be kept inactive (high) during write cycles to avoid bus contention. However, if the output bus has been enabled (\overline{CE} and \overline{OE} active) then \overline{WE} will disable the outputs in t_{ODW} from its falling edge.

DATA RETENTION MODE

The nonvolatile SRAM provides full functional capability for V_{CC} greater than 4.5 volts and write protects by 4.25V nominal (V_{CC} greater than 4.75V and write protect at 4.62V nominal for DS1235AB). Data is maintained in the absence of V_{CC} without any additional support circuitry. The DS1235Y/AB constantly monitors V_{CC} . Should the supply voltage decay, the RAM will automatically write protect itself; all inputs to the RAM become "don't care" and all outputs are high impedance. As V_{CC} falls below approximately 3.0 volts, the power switching circuit connects the lithium energy source to RAM to

retain data. During power-up, when V_{CC} rises above approximately 3.0 volts, the power switching circuit connects external V_{CC} to the RAM and disconnects the lithium energy source. Normal RAM operation can resume after V_{CC} exceeds 4.5 volts (4.75 volts for the DS1235AB).

FRESHNESS SEAL AND SHIPPING

The DS1235Y/AB is shipped from Dallas Semiconductor with the lithium energy source disconnected, guaranteeing full energy capacity. When V_{CC} is first applied at a level of greater than V_{TP} , the lithium energy source is enabled for battery backup operation.

BATTERY REDUNDANCY

Battery redundancy ensures reliability. The DS1235Y/AB contains two lithium energy cells separated by an internal isolation switch. During battery backup time the cell with the highest voltage is selected for use. If one battery fails, the other battery automatically takes over. The switch between batteries is transparent to the user.

ABSOLUTE MAXIMUM RATINGS*

Voltage on any Pin Relative to Ground	-0.3V to +7.0V
Operating Temperature	0°C to 70°C
Storage Temperature	-40°C to +70°C
Soldering Temperature	260°C for 10 seconds

* This is a stress rating only and functional operation of the device at these or any other conditions outside those indicated in the operation sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods of time may affect reliability.

RECOMMENDED DC OPERATING CONDITIONS

(0°C to 70°C)

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
DS1235Y Power Supply Voltage	V_{CC}	4.5	5.0	5.5	V	
DS1235AB Power Supply Voltage	V_{CC}	4.75	5.0	4.25	V	
Logic 1	V_{IH}	2.2		V_{CC}	V	
Logic 0	V_{IL}	0.0		+0.8	V	

(0°C to 70°C; $V_{CC}=5V \pm 10\%$ for DS1235Y)**DC ELECTRICAL CHARACTERISTICS**(0°C to 70°C; $V_{CC}=5V \pm 5\%$ for DS1235AB)

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
Input Leakage Current	I_{IL}	-1.0		+1.0	μA	
I/O Leakage Current $CE \setminus \geq V_{IH} \leq V_{CC}$	I_{IO}	-1.0		+1.0	μA	
Output Current @2.4V	I_{OH}	-1.0			mA	
Output Current @0.4V	I_{OL}	2.0			mA	
Standby Current $CE \setminus = 2.2V$	I_{CCS1}		5.0	10.0	mA	
Standby Current $CE \setminus = V_{CC}-0.5V$	I_{CCS2}		3.0	5.0	mA	
Operating Current	I_{CC01}			85	mA	
Write Protection Voltage (DS1235Y)	V_{TP}	4.25	4.37	4.5	V	
Write Protection Voltage (DS1235AB)	V_{TP}	4.50	4.62	4.75	V	

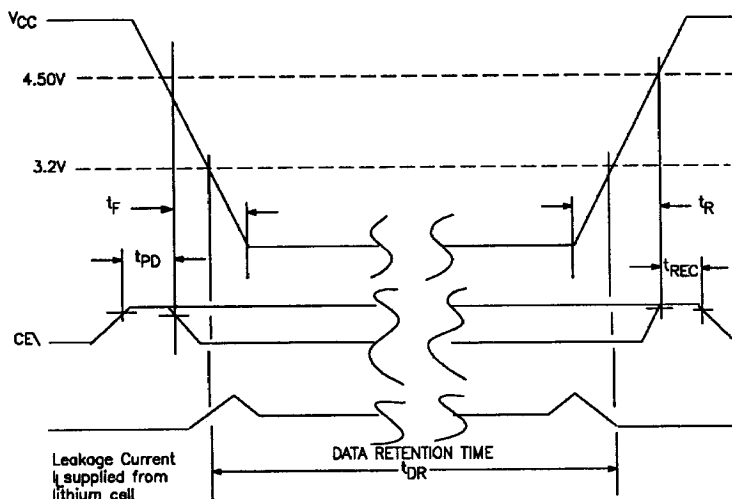
CAPACITANCE $(t_A=25^\circ\text{C})$

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
Input Capacitance	C_{IN}		5	10	pF	
Input/Output Capacitance	C_{IO}		5	12	pF	

 $(0^\circ\text{C to } 70^\circ\text{C}; V_{CC}=5.0\text{V} \pm 10\% \text{ for DS1235Y})$ **AC ELECTRICAL CHARACTERISTICS** $(0^\circ\text{C to } 70^\circ\text{C}; V_{CC}=5.0\text{V} \pm 5\% \text{ for DS1235AB})$

PARAMETER	SYM	DS1235Y/AB-100		DS1235Y/AB-120		DS1235Y/AB-150		DS1235Y/AB-200		UNITS	NOTES
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
Read Cycle Time	t_{RC}	100		120		150		200		ns	
Access Time	t_{ACC}		100		120		150		200	ns	
OE\ to Output Valid	t_{OE}		50		60		70		100	ns	
CE\ to Output Valid	t_{CO}		100		120		150		200	ns	
OE\ or CE\ to Output Active	t_{COE}	5		5		5		5		ns	5
Output High Z From De-selection	t_{OD}		35		40		70		100	ns	5
Output Hold From Address Change	t_{OH}	5		5		5		5		ns	
Write Cycle Time	t_{WC}	100		120		150		200		ns	
Write Pulse Width	t_{WP}	75		90		100		150		ns	3
Address Setup Time	t_{AW}	0		0		0		0		ns	
Write Recovery Time	t_{WR}	20		20		20		20		ns	
Output High Z From WE\	t_{ODW}		35		40		70		80	ns	5
Output Active From WE\	$t_{OE\text{W}}$	5		5		5		5		ns	5
Data Setup Time	t_{DS}	40		50		60		80		ns	4
Data Hold Time	t_{DH}	20		20		20		20		ns	4

POWER-DOWN/POWER-UP CONDITION



POWER-DOWN/POWER-UP TIMING

SYM	PARAMETER	MIN	MAX	UNITS	NOTES
t_{PD}	$CE\backslash$ at V_{IH} before Power-Down	0		μs	
t_F	V_{CC} slew from 4.5V to 0V ($CE\backslash$ at V_{IH})	300		μs	
t_R	V_{CC} slew from 0V to 4.5V ($CE\backslash$ at V_{IH})	0		μs	
t_{REC}	$CE\backslash$ at V_{IH} after Power-Up	2	125	ms	

($t_A = 25^\circ C$)

SYM	PARAMETER	MIN	MAX	UNITS	NOTES
t_{DR}	Expected Data Retention Time	5		years	9

WARNING:

Under no circumstance are negative undershoots, of any amplitude, allowed when device is in battery backup mode.

NOTES

1. \overline{WE} is high for a read cycle.
2. $\overline{OE} = V_{IH}$ or V_{IL} . If $\overline{OE} = V_{IH}$ during write cycle, the output buffers remain in a high impedance state.
3. t_{WP} is specified as the logical AND of \overline{CE} and \overline{WE} .
 t_{WP} is measured from the latter of \overline{CE} or \overline{WE} going low to the earlier of \overline{CE} or \overline{WE} going high.
4. t_{DH} , t_{DS} are measured from the earlier of \overline{CE} or \overline{WE} going high.
5. These parameters are sampled with a 5 pF load and are not 100% tested.
6. If the \overline{CE} low transition occurs simultaneously with or later than the \overline{WE} low transition in Write Cycle 1, the output buffers remain in a high impedance state during this period.
7. If the \overline{CE} high transition occurs prior to or simultaneously with the \overline{WE} high transition in write Cycle 1, the output buffers remain in a high impedance state during this period.
8. If \overline{WE} is low or the \overline{WE} low transition occurs prior to or simultaneously with the \overline{CE} low transition, the output buffers remain in a high impedance state during this period.
9. Each DS1235Y/AB has a built-in switch that disconnects the lithium source until V_{CC} is first applied by the user. The expected t_{DR} is defined as accumulative time in the absence of V_{CC} starting from the time power is first applied by the user.

DC Test Conditions

Outputs Open
 $t_{\text{Cycle}} = 200\text{ns}$
 All Voltages Are Referenced to Ground

AC Test Conditions

Output Load: 100 pF + 1TTL Gate
 Input Pulse Levels: 0-3.0V
 Timing Measurement Reference Levels
 Input: 1.5V
 Output: 1.5V
 Input Pulse Rise and Fall Times: 5ns